

What is claimed is:

1 1. A heat dissipating apparatus for an electronic
2 device having an integrated heat spreader, comprising:

3 a base having a lower surface and an upper surface,
4 the lower surface having a contact area to
5 contact the integrated heat spreader when the
6 base is disposed on the electronic device, and
7 the lower surface having a concave area
8 extended to the contact area from an edge of
9 the lower surface of the base.

1 2. The heat dissipating apparatus as claimed in
2 claim 1, wherein the contact area of the base is
3 connected to the integrated heat spreader by means of
4 thermal paste.

1 3. The heat dissipating apparatus as claimed in
2 claim 2, wherein the thermal paste is composed of a phase
3 change material.

1 4. The heat dissipating apparatus as claimed in
2 claim 1, wherein the base further comprises a plurality
3 of fins formed on the upper surface thereof.

1 5. The heat dissipating apparatus as claimed in
2 claim 1, wherein the cross section of the concave area is
3 rectangular.

1 6. The heat dissipating apparatus as claimed in
2 claim 1, wherein the cross section of the concave area is
3 semicircular.

. 1 7. The heat dissipating apparatus as claimed in
2 claim 1, wherein the cross section of the concave area is
3 triangular.

. 1 8. The heat dissipating apparatus as claimed in
2 claim 1, wherein the integrated heat spreader and contact
3 area are substantially rectangular.

. 1 9. The heat dissipating apparatus as claimed in
2 claim 1, wherein the electronic device is a central
3 processing unit (CPU).

. 1 10. A heat dissipating apparatus, disposed on an
2 electronic device having an integrated heat spreader,
3 comprising:

. 4 a base having a concave area and a contact area,
5 wherein the contact area is connected to the
6 integrated heat spreader, the shape and
7 position of the contact area correspond to the
8 shape and position of the integrated heat
9 spreader, and the concave area is extended to
10 the contact area from an edge of the base; and
11 a thermal paste disposed between the contact area
12 and integrated heat spreader.

. 1 11. The heat dissipating apparatus as claimed in
2 claim 10, wherein the thermal paste is composed of a
3 phase change material.

. 1 12. The heat dissipating apparatus as claimed in
2 claim 10, wherein the base further comprises a plurality
3 of fins formed thereon.

1 13. The heat dissipating apparatus as claimed in
2 claim 10, wherein the cross section of the concave area
3 is rectangular.

1 14. The heat dissipating apparatus as claimed in
2 claim 10, wherein the cross section of the concave area
3 is semicircular.

1 15. The heat dissipating apparatus as claimed in
2 claim 10, wherein the cross section of the concave area
3 is triangular.